

D2 42. (Twice Amended) A semiconductor device comprising:

a semiconductor element having protruding electrodes formed on a surface thereof;
a first compressed resin layer that is formed on the surface of the semiconductor element and
seals lateral surfaces of the protruding electrodes [except for ends thereof]; and
a second compressed resin layer provided so as to cover at least a back surface of the
semiconductor element.

43. (Twice Amended) A semiconductor device comprising:

a semiconductor element having protruding electrodes formed on a surface thereof;
a compressed resin layer which is formed on the surface of the semiconductor element and
seals lateral surfaces of the protruding electrodes [except for ends thereof]; and
external connection protruding electrodes provided to the ends of the protruding electrodes
exposed from the resin layer.

57. (Twice Amended) A semiconductor device comprising:

[a single or] a plurality of semiconductor elements;

a compressed sealing resin which seals partially or totally the semiconductor [element or]

D3 elements; and

an electrode plate which is provided in the compressed sealing resin and is electrically
connected to the semiconductor [element or] elements, the electrode plate having portions which are
exposed from side surfaces of the compressed sealing resin and function as external connection
electrodes.

D4 62. (Twice Amended) The semiconductor device as claimed in claim 60, wherein the
protruding terminals are [the] protruding electrodes arranged to the electrode plate.

71. (Three Times Amended) A mounting arrangement for mounting a semiconductor device on a mounting board, the semiconductor device comprising:

[a single or] a plurality of semiconductor elements;

a compressed sealing resin which seals partially or totally the semiconductor [element or] elements;

an electrode plate which is provided in the sealing resin and is electrically connected to the semiconductor [element or] elements, the electrode plate having portions which are exposed from side surfaces of the compressed sealing resin and function as external connection electrodes; and

protruding terminals provided to the electrode plate, and exposed from a bottom surface of the compressed sealing resin, so that protruding terminals function as external connection terminals;

the mounting arrangement comprising:

bumps arranged to the protruding terminals for forming the external connection

terminals,

the semiconductor device being connected to the mounting board through the bumps.

79. (Amended) A semiconductor device comprising:

a semiconductor device main body having a semiconductor element having a surface on which protruding electrodes are directly formed, and a compressed resin layer which is formed on the surface of the semiconductor element and seals lateral surfaces of the protruding electrodes [except for ends thereof];

an interposer to which the semiconductor device main body is attached, a wiring pattern to which the semiconductor device main body is connected being formed on a base member of the interposer;

an adhesive which is provided between the semiconductor device main body and the interposer and which bonds the semiconductor device main body to the interposer;
a conductive member which electrically connects the semiconductor device main body and the interposer; and
external connection terminals which are connected to [the] wiring pattern through holes formed in the base member and are arranged on a surface of the semiconductor device main body opposite to the surface on which the protruding electrodes are provided.

90. (Amended) A semiconductor device comprising:
a semiconductor element having a surface on which external connection electrodes are provided, which are to be electrically connected to external terminals; and
a compressed resin layer provided on the surface of the semiconductor elements so as to cover the external connection electrodes,
wherein the external connection electrodes are exposed at a lateral surface of the compressed resin layer, the lateral surface of the resin layer and the lateral surface of the semiconductor element have planes cut by a dicer.

91. (Amended) A semiconductor device comprising:
a semiconductor element having a surface on which protruding electrodes are formed;
and
a resin layer which is formed on the surface on the semiconductor element and seals a lateral surface and a top of the protruding electrodes, the resin layer slightly covering upper portions of the protruding electrodes.
wherein the lateral surface of the resin layer and the lateral surface of the semiconductor element have planes cut by a dicer.

97. (Amended) The semiconductor device as claimed in claim 88, wherein the [resin sealing step disposes] compressed resin layer is formed by disposing a film between the protruding electrodes and [the] a mold, which thus contacts the sealing resin through the film.

98. (Amended) The semiconductor device as claimed in claim 88, wherein [the resin sealing step uses] a sheet-shaped resin is used as the sealing resin.

99. (Amended) The semiconductor device as claimed in claim 88, wherein a reinforcement plate is loaded onto [the] a mold before the substrate is loaded onto the mold in [the resin sealing step] forming the compressed resin layer.

100. (Amended) The semiconductor device as claimed in claim 88, wherein:
[the] a film used in [the resin sealing step] forming the compressed resin layer is formed of an elastically deformable substance, and the ends of the protruding electrodes are caused to fall in the film when the resin layer is formed by using [the] a mold; and

the film is detached from the resin layer [in] when the protruding electrode [exposing step] is exposed so that the ends of the protruding electrodes can be exposed from the resin layer.

102. (Amended) The semiconductor device as claimed in claim 88, wherein the [sealing resin used in the resin sealing step] compressed resin layer comprises a plurality of sealing resins having different characteristics.

REMARKS

Claims 18, 19, 36, 41-43, 54-64, 70-77, 79-85, 90, 91 and 95-107 are pending. Claims 1-12, 20-35, 37-40, 44-53, 65-69, 78, 86, 92-94 and 108 are canceled without prejudice or disclaimer. Claims 18, 42, 43, 57, 62, 71, 79, 90, 91, 97-100 and 102 are amended.